**Package Outline Drawing**

**W4x5.20A**

20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 1, 1/12

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**NOTES:**


2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.

3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.

4. Bump position designation per JESD 95-1, SPP-010.

5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.